

Method for Bonding at Least Three Substrates

Abstract

The invention relates to a method for bonding at least three substrates (4o, 4u, 4, 4', 4'', 4''', 4o') to form a substrate stack (9, 9', 9''), wherein the substrate stack (9, 9', 9'') has at least one lowermost substrate (4u, 4), a middle substrate (4o, 4'), and an upper substrate (4o', 4''), comprising the following steps:

- aligning the middle substrate (4o, 4') to the lowermost substrate (4u, 4) and bonding the middle substrate (4o, 4') to the lowermost substrate (4u, 4), then aligning the upper substrate (4o', 4'') and bonding the upper substrate (4o', 4'') to the middle substrate (4o, 4), wherein the upper substrate (4o', 4'') is aligned to the lowermost substrate (4u, 4).

Figure 2h